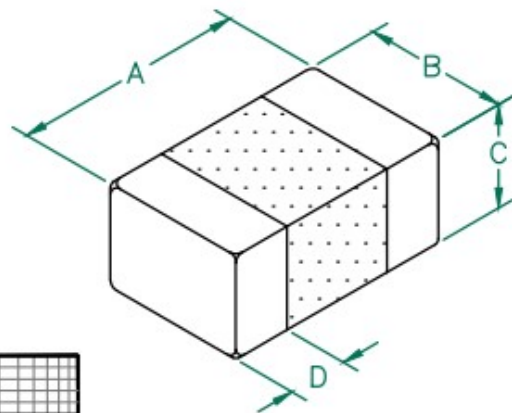


# HI0805R800R-10

## PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]



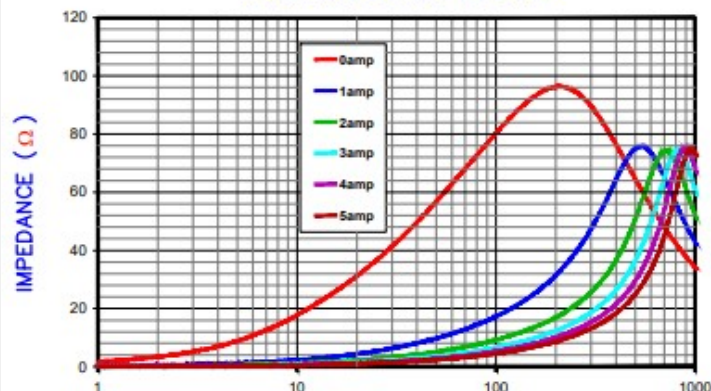
## ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	80	
Minimum	60	
Maximum	100	0.010 5000 mA

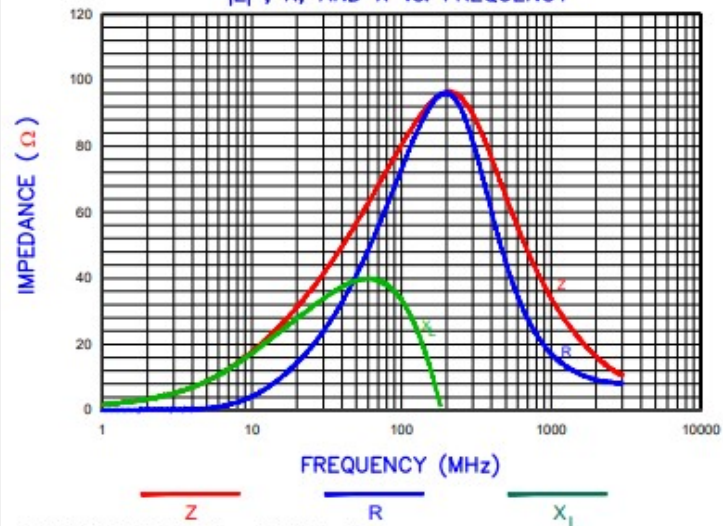
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REE, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. CONTINUOUS CURRENT RATING OF 5000 mA.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

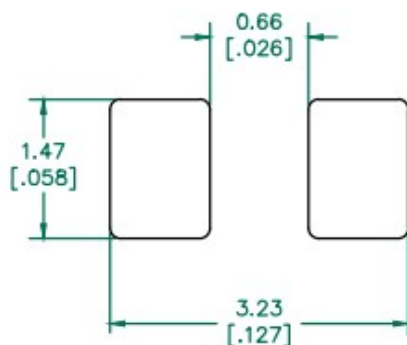
Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)  
|Z|, R, AND X vs. FREQUENCY

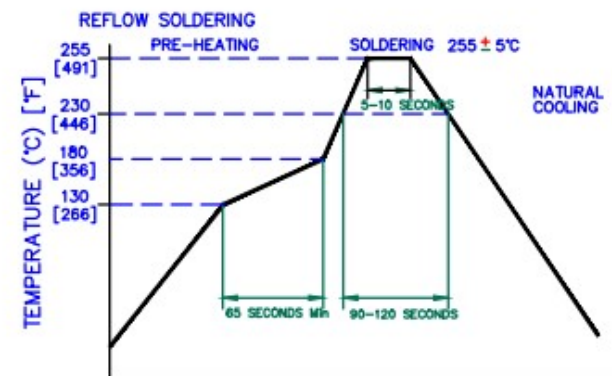


## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

## RECOMMENDED SOLDERING CONDITIONS



RoHS

DIMENSIONS ARE IN mm [INCHES].

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E	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER: <b>HI0805R800R-10</b>	REV: <b>E</b> PART TYPE: <b>CO-FIRE</b> DRAWN BY: <b>TMB</b>
D	CHANGE TO PAPER TAPE	03/03/10	JUN	DATE: <b>04/02/04</b>	SCALE: <b>NTS</b> SHEET: <b>1 of 1</b>
C	UPDATE COMPANY LOGO	06/15/09	JRK	CAD # <b>HI0805R800R-10-E</b>	TOOL # <b>-</b>
B	UPDATE COMPANY LOGO	01/17/08	JRK		
A	ORIGINAL DRAFT	04/02/04	TMB		
REV	DESCRIPTION	DATE	INT		